

QUOTATION

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IOPCAS-BEIJING will pay INESC-MN for the completed design and development of TMR Sensors as per the SOW, in the amount of One Hundred Thousand Euro (100,000 €), in two milestone payments. INESC-MN will send invoice to IOP-BEIJING according the schedule herein. Invoice will be paid by IOP-BEIJING in Euro within thirty (30) days after receipt of an electronic invoice from INESC-MN. The following quotation is available before Jan. 31. 2022.

- a. Euro 50,000 (50% of 100,000 €) with the signature of the Cooperation Agreement, for sensor optimization and test.
- b. Euro 50,000 (50% of 100,000 €) on the Deliverable of 40 TMR sensor wafers and technical description.
- c. Sensor performance will be evaluated in a best effort basis. The Parties should agree on the acceptance conditions in the SOW.
- d. Additional wafers with TMR sensors to be sourced from INESC-MN shall be Euro 1,500 per wafer.

Annex A - Statement of Work (SOW)

Development of MTJ sensors at INESC MN will be done in two phases:

Phase 1 - TMR sensors with direct and indirect double pinned MTJ structures will be optimized with the structures:

[Ta/Ru]3/PtMn/CoFe/Ru/CoFeB/MgO/CoFeB/NiFe/Ru/IrMn/Ta/Ru

Or similar indirect & direct double pinned structures optimized at INESC-MN.

The full bridge chip size is as small as possible.

The specifications of the optimized devices are:

(1) Full bridge Resistance : 10 k Ω ~ 50 k Ω ;

Sensitivity : 5~10 mV/V/Oe;
Offset voltage: min -5 mV/V, max 5 mV/V;
Field noise level (Detectivity): $\sim 1 \text{ nT/Hz}^{(1/2)}$ @1Hz;
Non-linearity: <0.5%;
Saturation field: >100 Oe;
Hysteresis: <0.5 Oe @ $\pm 80 \text{ Oe}$ @25°C;
Uniformity: >95%;
Bandwidth: DC~1 MHz;
Temperature Coefficient of Resistance <600 ppm/°C;
Temperature Coefficient of Sensitivity <300 ppm/°C.

(2) Full bridge Resistance : 10 k Ω ~50 k Ω ;

Sensitivity : 0.1~1 mV/V/Oe;
Offset voltage: min -5 mV/V, max 5 mV/V @ $\pm 200 \text{ Oe}$;
Field noise level (Detectivity): $\sim 1 \text{ nT/Hz}^{(1/2)}$ @1Hz;
Non-linearity: <0.5%;
Saturation field: >500 Oe;
Hysteresis: <0.5 Oe @ $\pm 200 \text{ Oe}$ @25°C;
Uniformity: >95%;
Bandwidth: DC~1 MHz;
Temperature Coefficient of Resistance <600 ppm/°C;
Temperature Coefficient of Sensitivity <300 ppm/°C.

The sensors will be optimized at test sample level, including magnetic and transport characterization. The test samples will be available to IOP-BEIJING, together with the reports.

Phase 2 – TMR wafer production - A microfabrication process will be developed for 6 inch or 8 inch wafers. The objective is to demonstrate a full wafer process capability, with high yield (> 90% functional devices) and within the specifications.

Deliverable: INESC-MN will provide up to 20 wafers of 6 inch and 20 wafers of 8 inch with the optimized stacks and design.

Name: Susana Cardoso de Freitas

Title: co-director